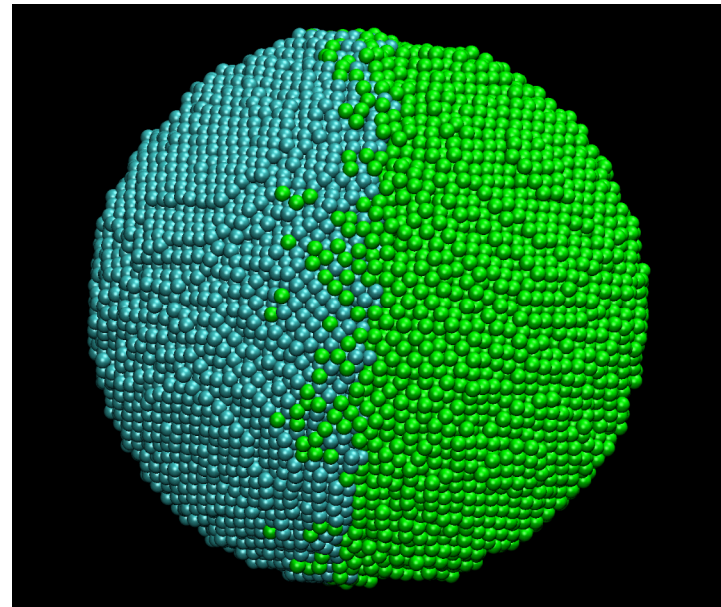
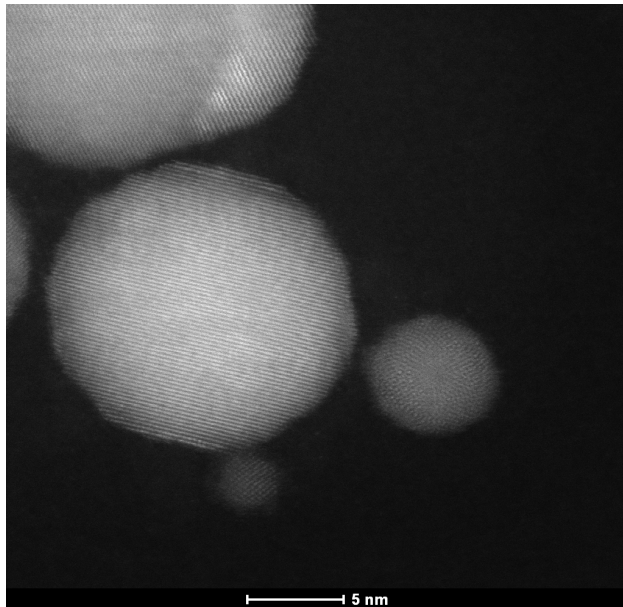


# Bonding of Metallic Nanoparticles SAND2013-3557C

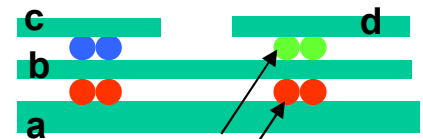
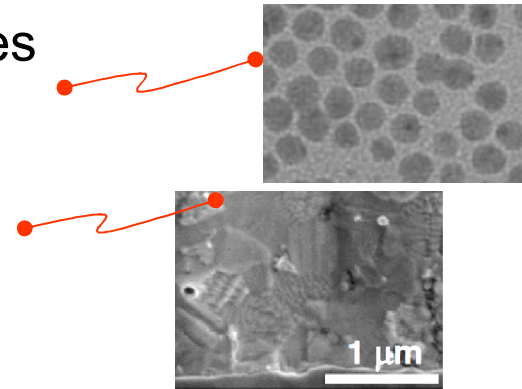
*Michael Chandross, T. Boyle, B. Clark, P. Lu*

*Sandia National Laboratories, Albuquerque NM 87123*



# Nanoparticle Solders

- Metallic NP nanosolders offer two advantages
  - Low processing temperatures
  - High service temperatures
- Example: Ag/Cu
  - Bonding at  $\sim 200^{\circ}\text{C}$
  - Applications above  $350^{\circ}\text{C}$
- Enable step-soldering for stacked (3D) package
  - Increases functionality, reliability
  - Does not increase footprint
- Critical parameters controlling the metal/metal interfacial reactions are not understood

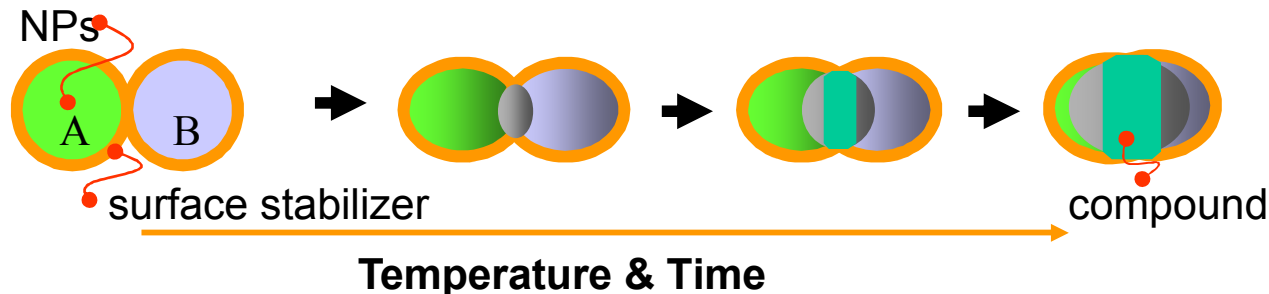


Different color shows different soldering steps

# R&D Goals & Approach

**Goals:** *Identify, understand and control* the key properties that affect bonding formations at NP metal interfaces

- *In-situ*, dynamic TEM observation & Atomic-scale MD modeling

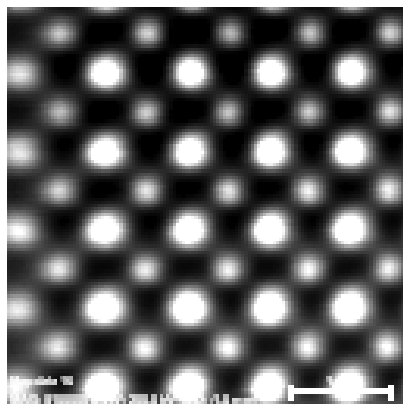


- *In-situ*, aberration-corrected STEM will be used to obtain *atomic-scale, compositional maps* (at T, t).
- *Direct comparison* between the experiment and theory (MD) will be used to understand the reaction model.

# Aberration Corrected STEM

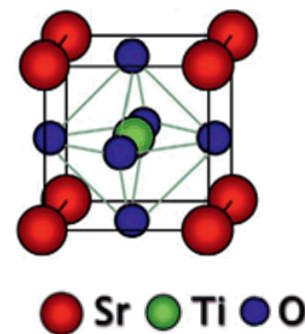
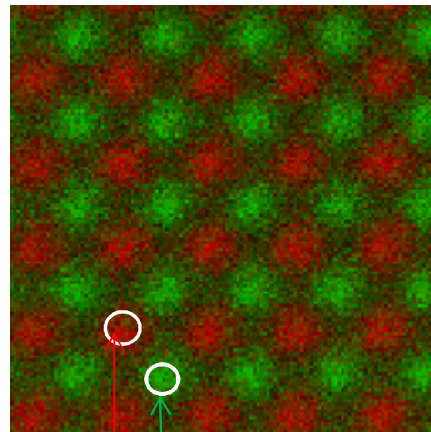


HAADF Z-contrast imaging



1.8nm

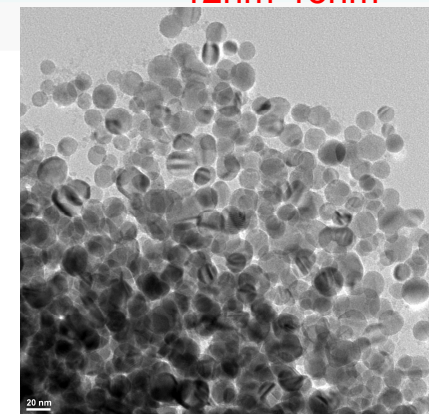
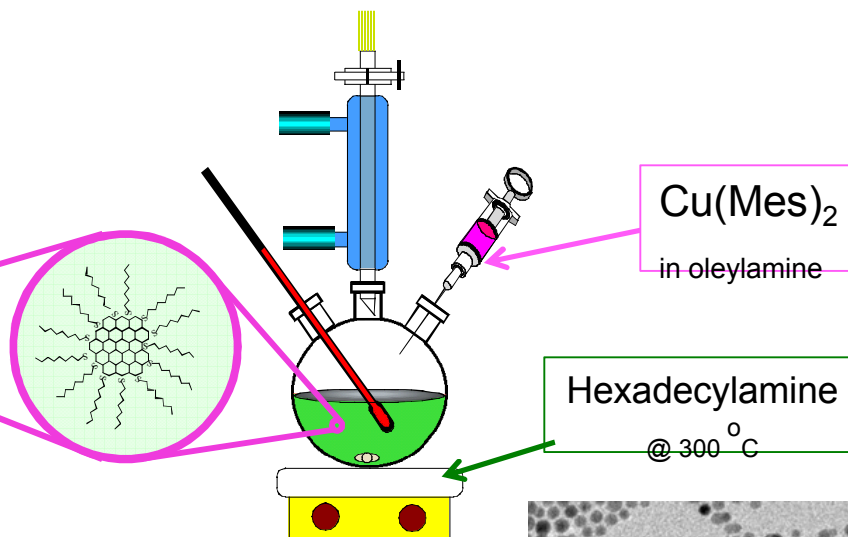
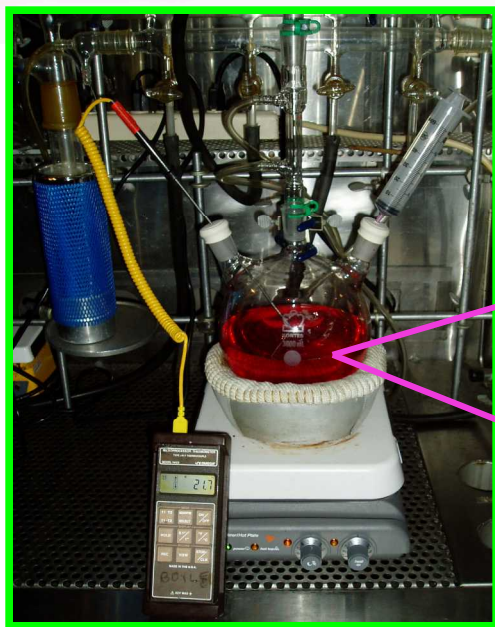
Atomic-scale element map



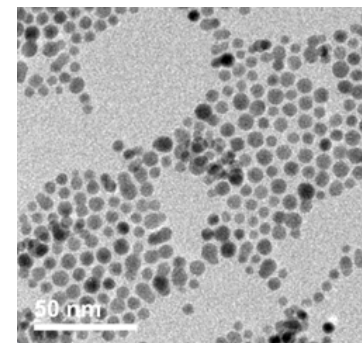
- FEI Titan G2 with *ChemiSTEM Technology*
  - Advanced spherical aberration correction
  - Super-bright field emission electron gun
  - Four Si drift detectors
  - 1000°C/sec thermal ramp
- Unprecedented capabilities
  - Sub-atomic scale STEM (80-120 pm)
  - Atomic scale chemical mapping
  - Light element detection
  - Low energy operation for sensitive materials



# Nanoparticle Creation

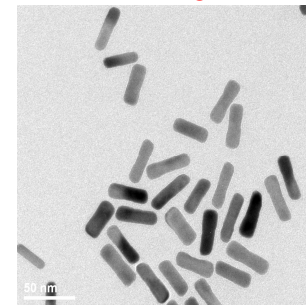


Cu NPs  
~12nm-15nm



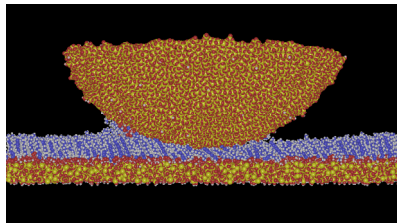
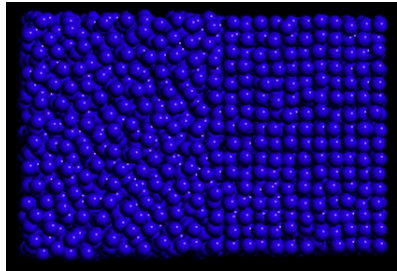
Ag NPs  
~6nm

Au NP rods  
~12nm x 26nm



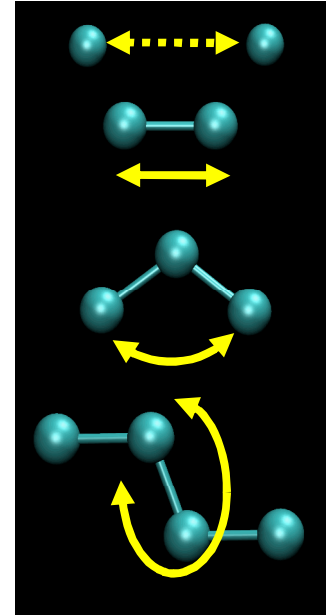
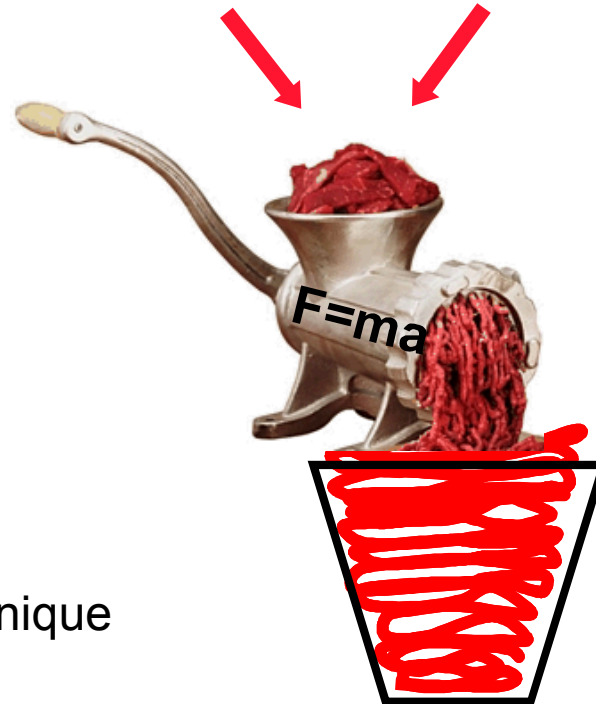
- Solution Precipitation – inject something cold into something hot
- Variety of particles
- Different shapes. sizes
  - Spheres
  - Rods

# Molecular Dynamics Modeling



Initial positions  
and velocities

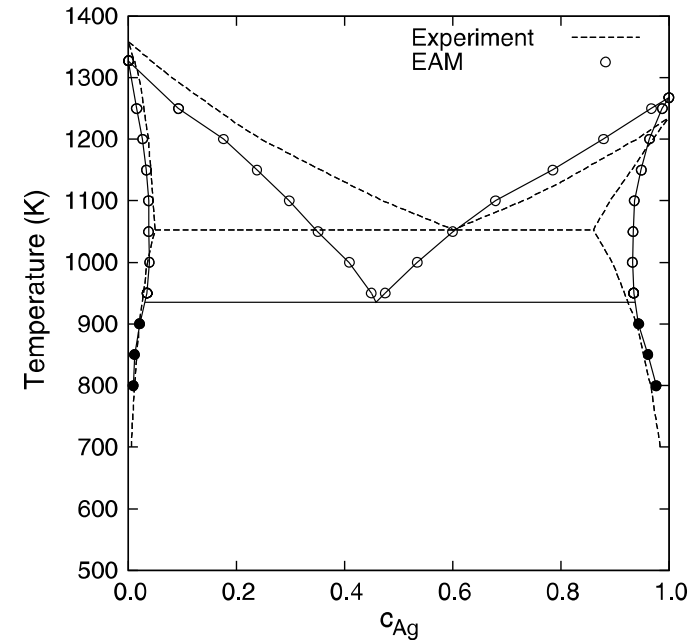
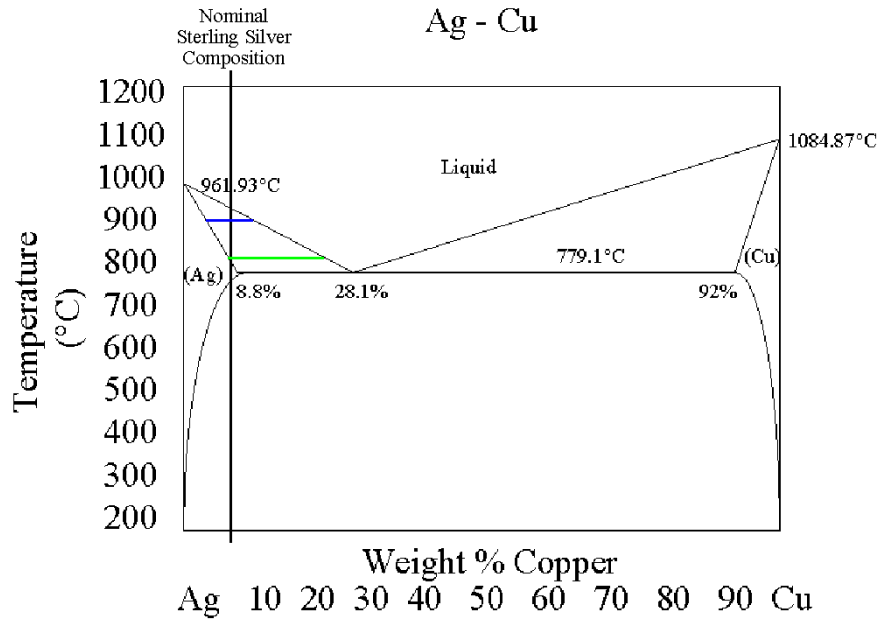
Interatomic  
potential



Positions and  
velocities at  
later times

- Classical simulation technique
- Empirical interactions
- Evolve system, analyze
- Also performed Monte Carlo substitutions

# Ag/Cu Phase Diagram



- Eutectic system
- Not miscible
- This is bulk, is nanoscale different?
- Model phase diagram matches very well

# Initial Experiments

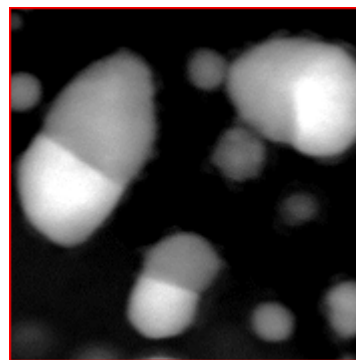
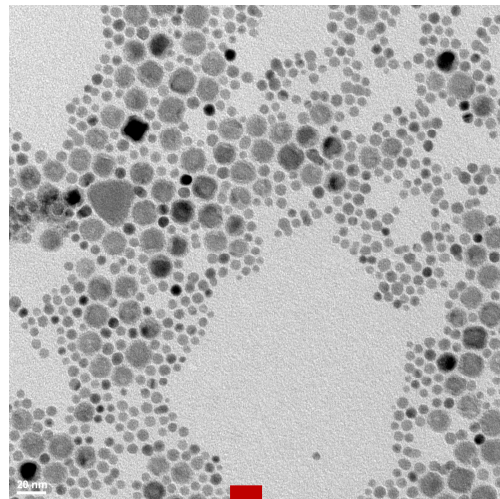
Cu/Ag dispersed on C film

Ag – 5-6 nm

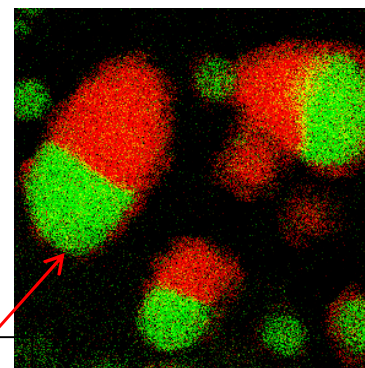
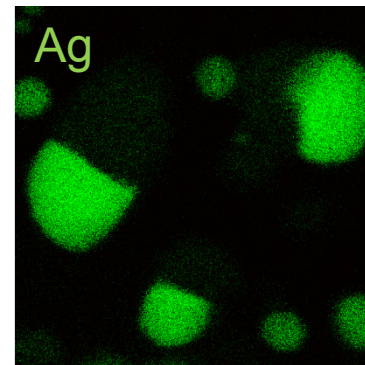
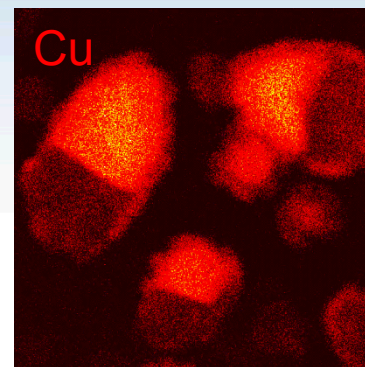
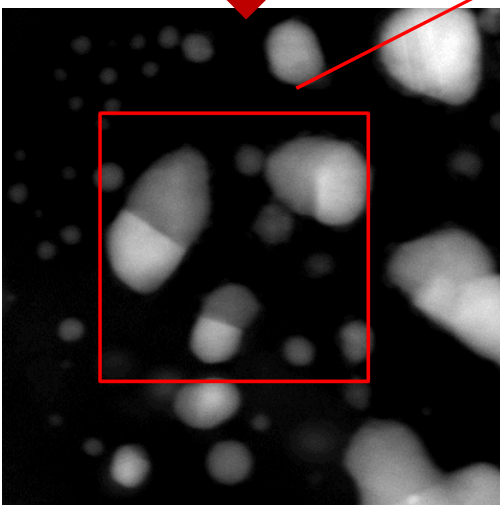
Cu – 12-15nm

300°C

1 minute



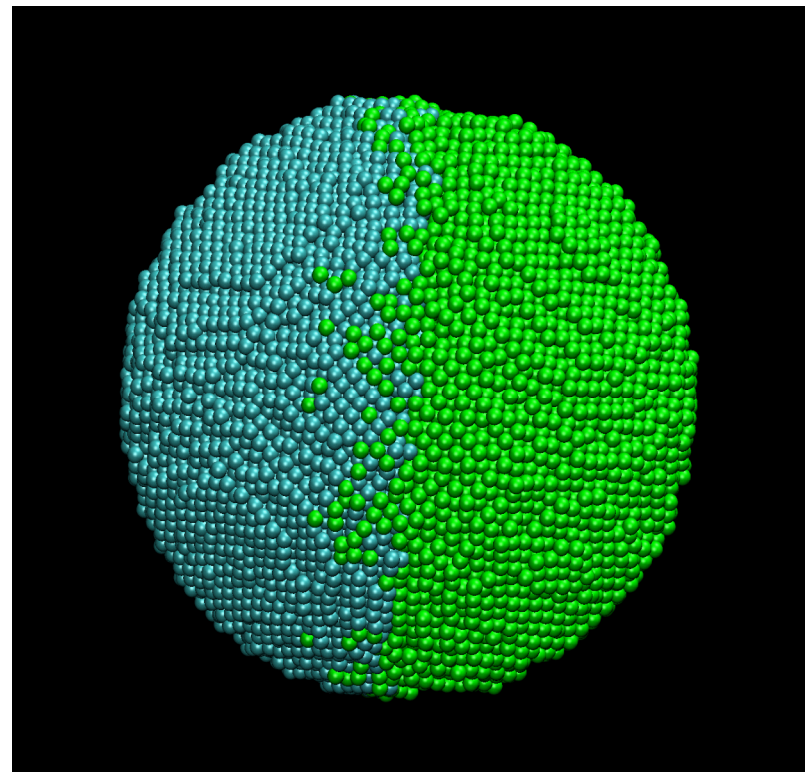
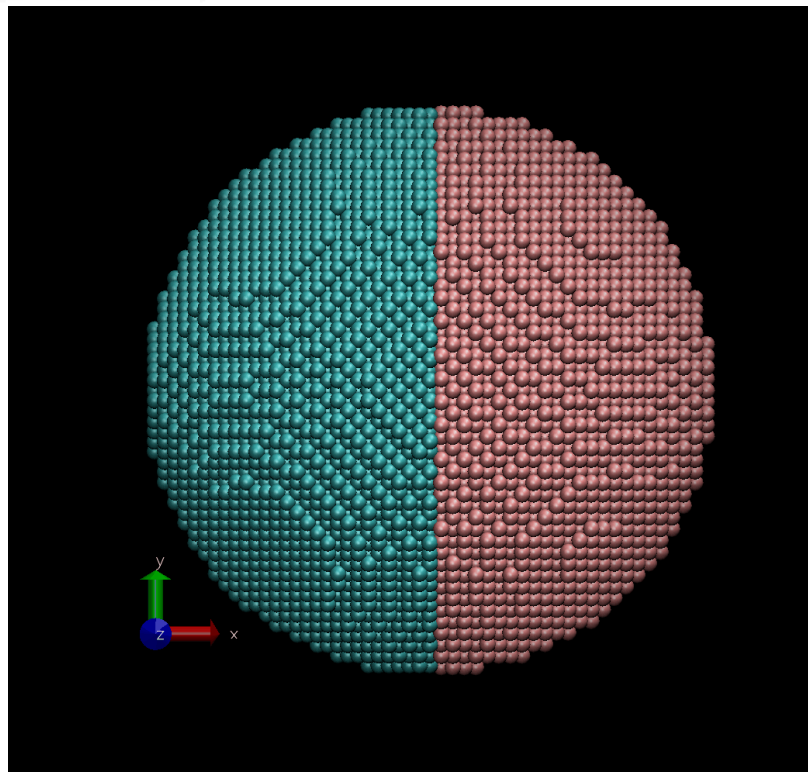
105nm



Thin layer of Cu  
around Ag !



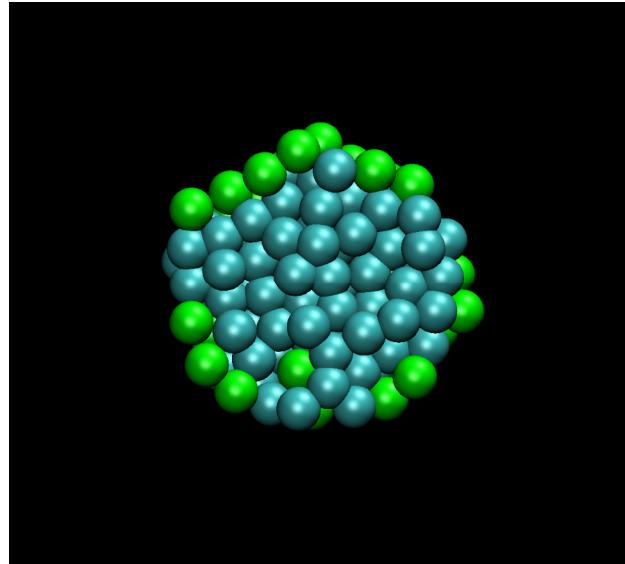
# Simulation Results



- 10nm Janus nanoparticles (left half Cu, right half Ag)
- At 800K (below eutectic) for  $< 1$  ns
- Shows opposite behavior

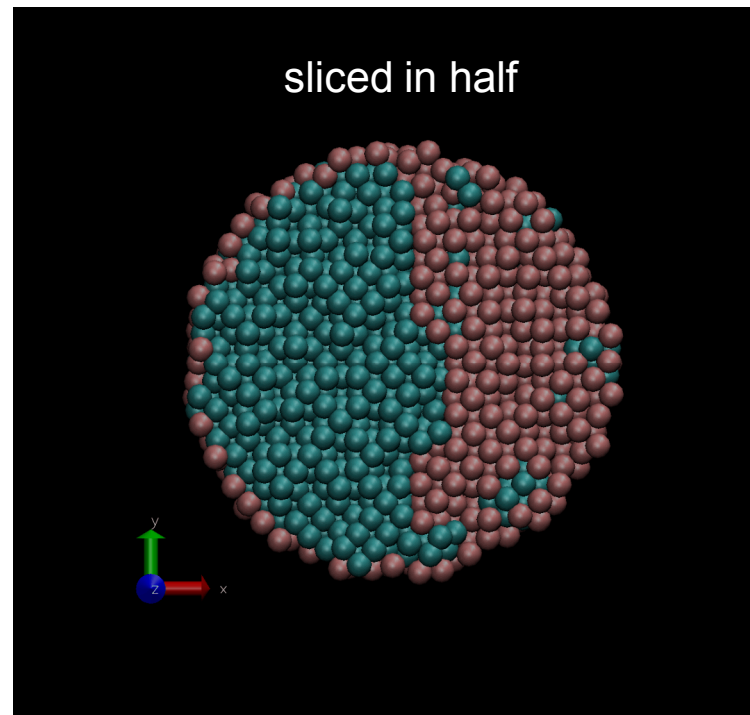
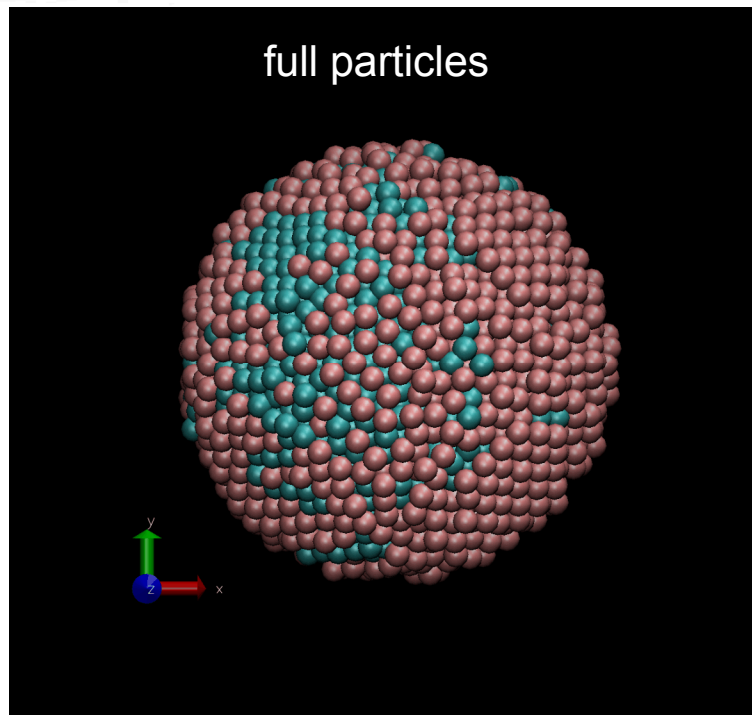


# Smaller Particles



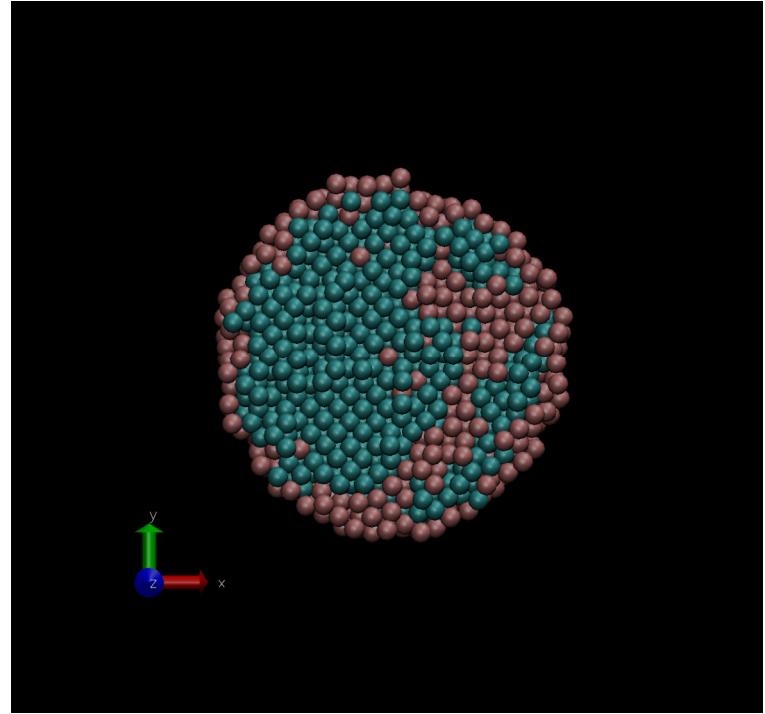
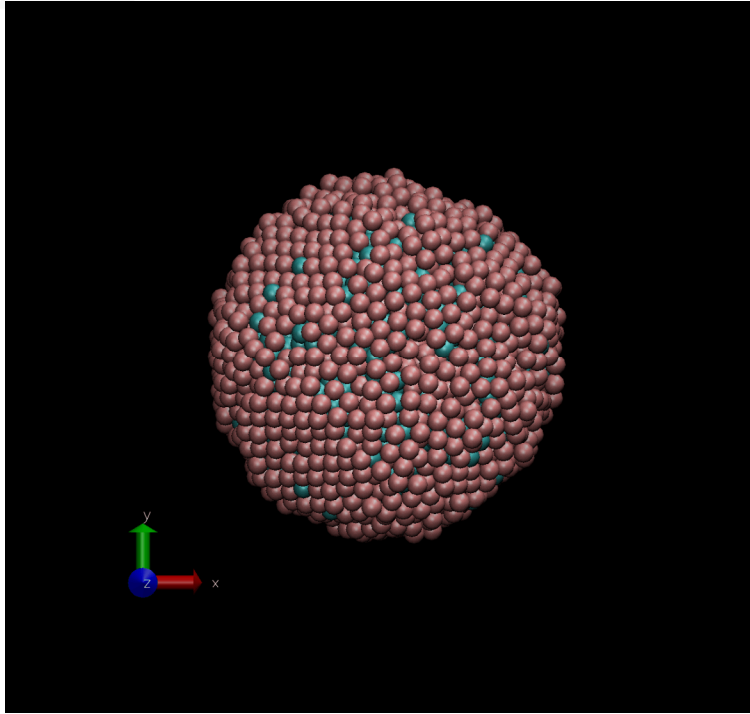
- 800K for 12.5 ns
- Particle cut in half for detail
- Complete silver shell formed

# Monte Carlo Simulations



- Simulation is not real time, but can be slow
- Randomly pick two particles to swap (with small translation)
- Accept move if energy is lower, or according to Boltzmann
- 5nm particle after 20M steps

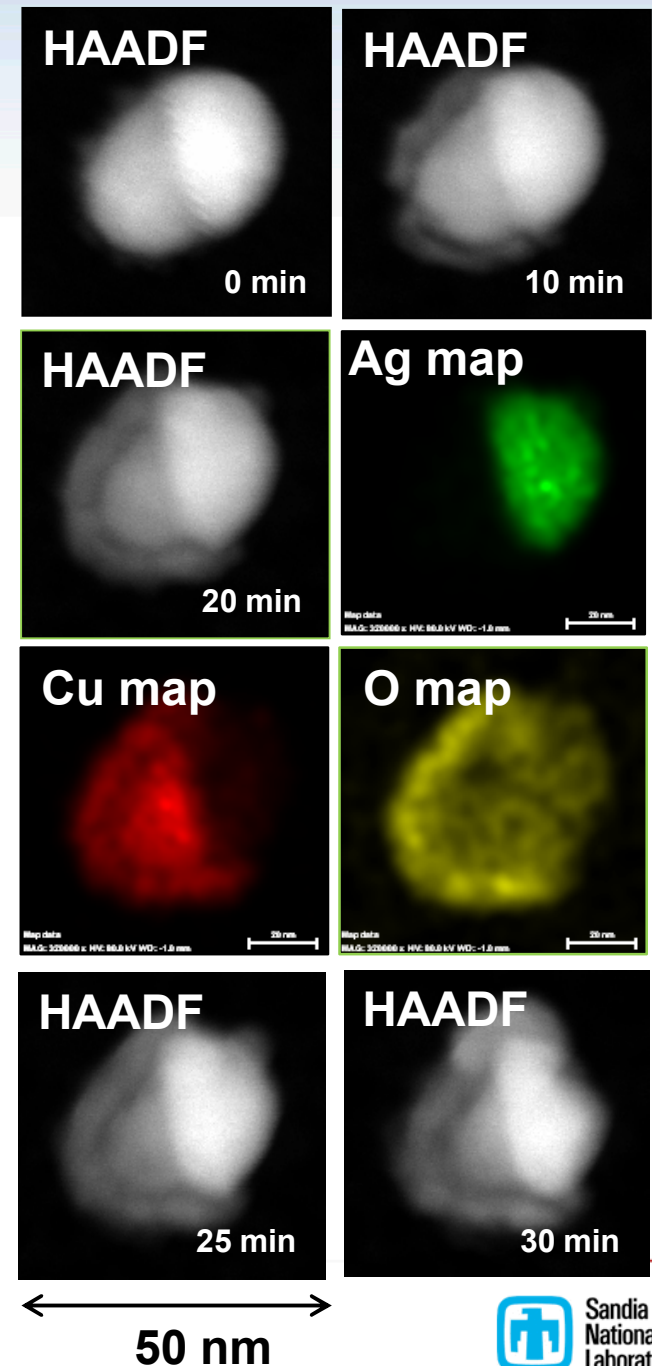
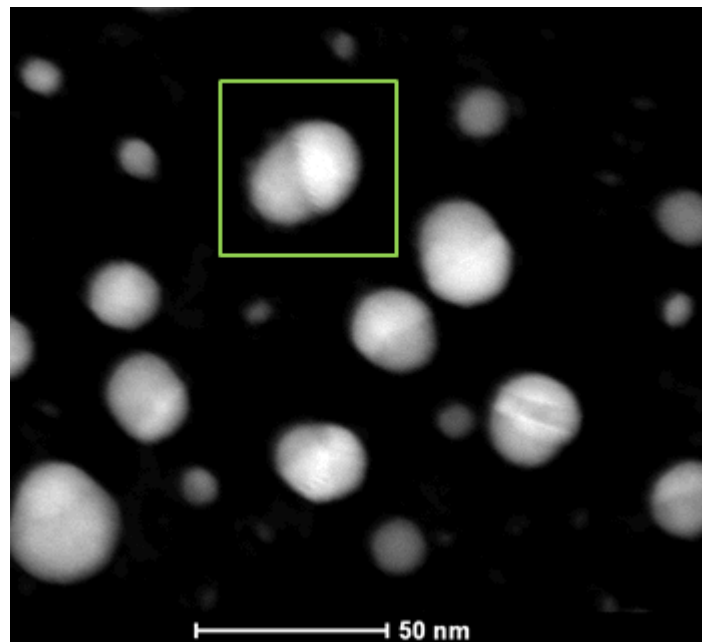
# Longer Time Results



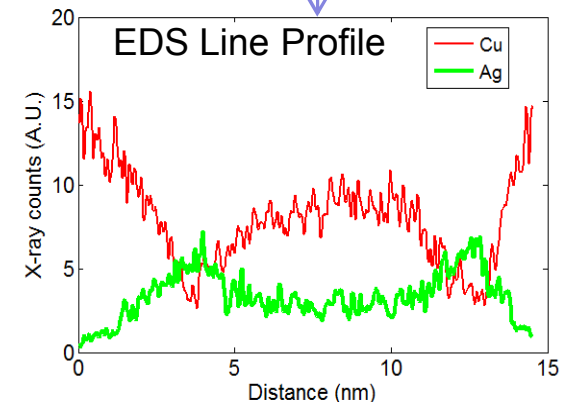
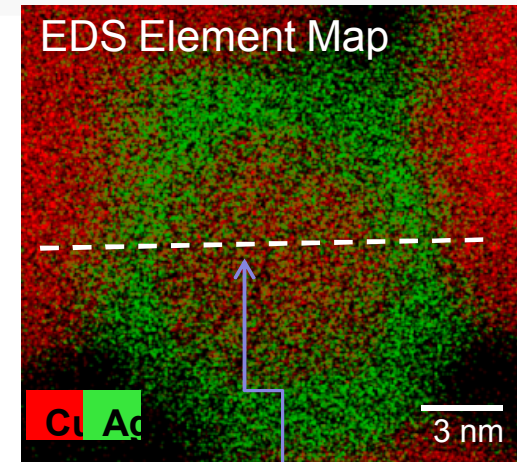
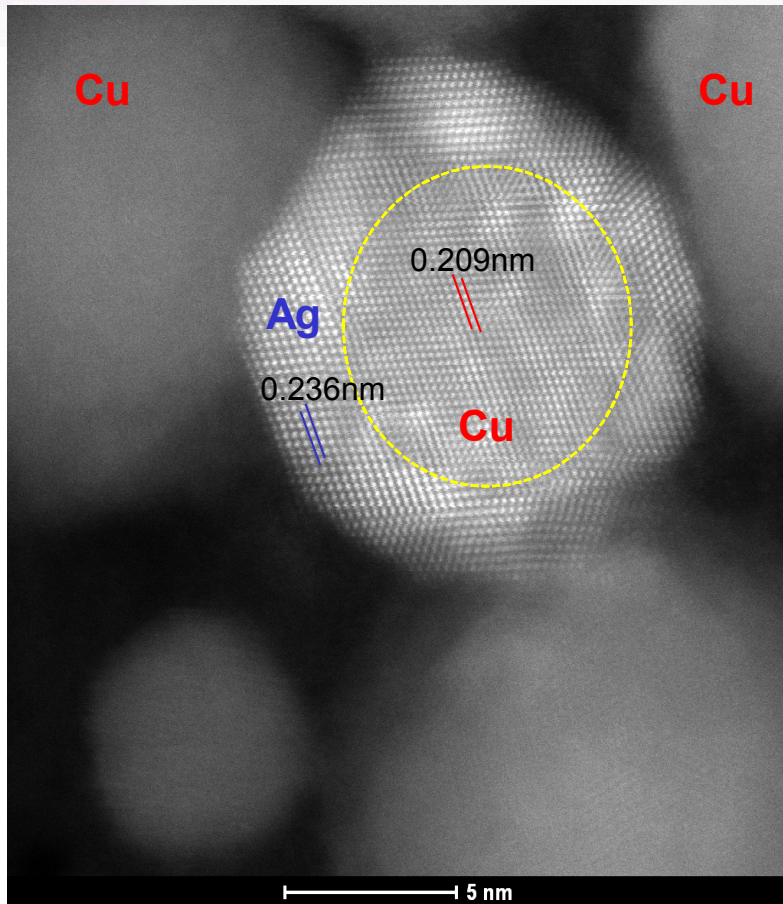
- 5nm, after 60M steps
- Shell is clearly favored at 800K

# In-Situ TEM Challenges

- Electron beam induced effect
  - Electron beam exposure, even at 80 kV, during the EDS mapping leads to oxidation of Cu NPs
- Sample drift during heating and cooling



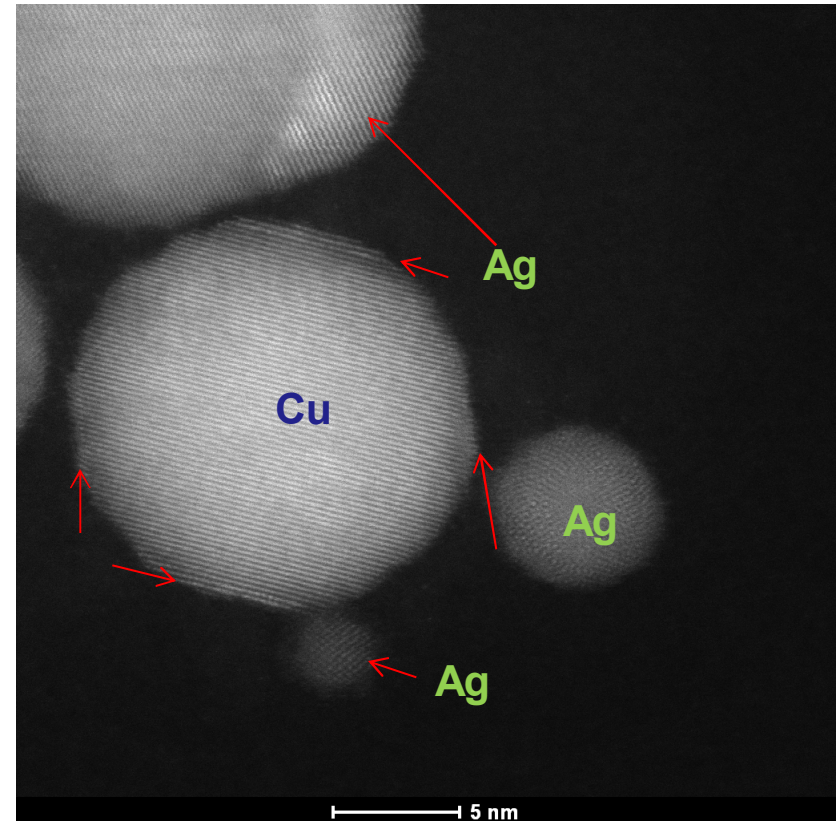
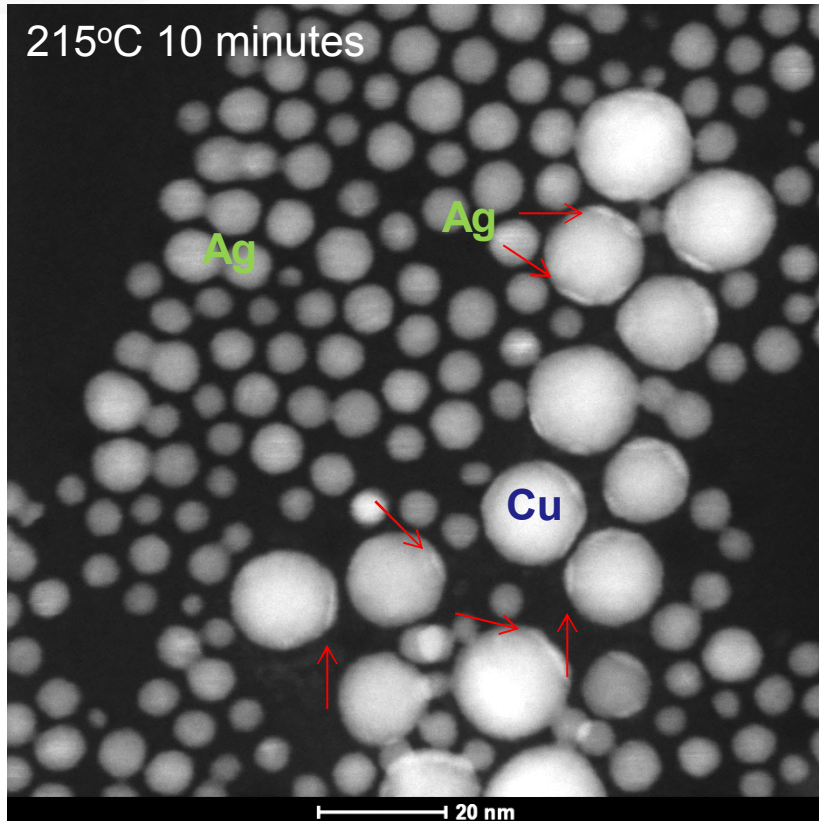
# New Experimental Results



- Results from heating to 150°C
- Carefully avoid electron beam heating
- Now agrees with prediction from simulations
- ~9nm Cu core with ~2.5nm Ag-shell, preference for {111}

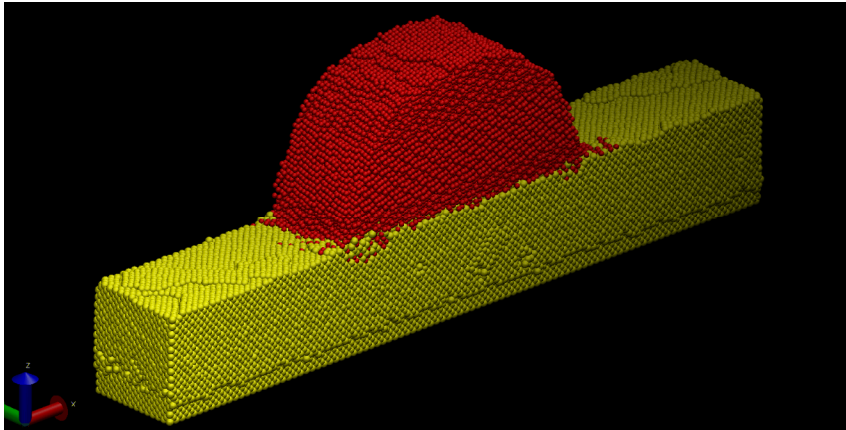


# Further Demonstration of {111}

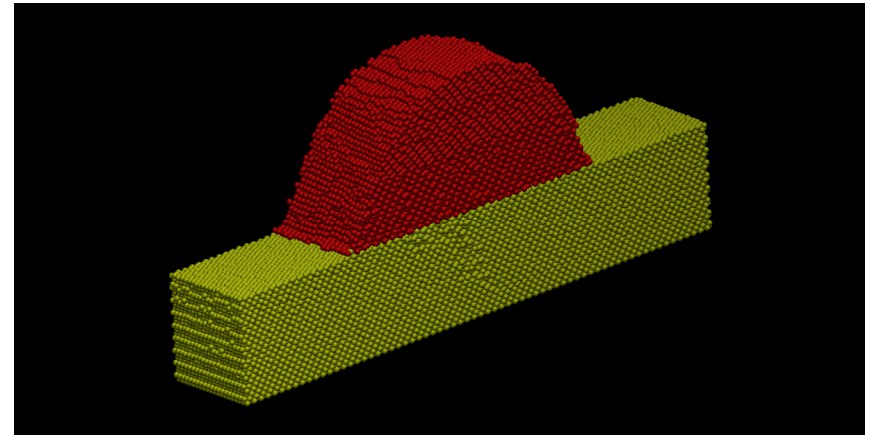


- Slightly higher temperature
- Ag shell caught in the act of formation
- Demonstrates preference for {111} formation

# Why {111}?



Ag on Cu{100}  
~ 10 ns



Ag on Cu{111}  
~ 20 ns

- Simulations of sessile drop spreading
- Run with MD at 500°C
- Infinite half-cylinder on infinite substrate
  - psuedo-2D version of drop
  - Same spreading dynamics
- Not much spreading on {100} or {111}

# Why {111}?

## Interfacial Energies

	Ag(100)	Ag(111)
Cu(100)	5.2 J/m <sup>2</sup>	4.3 J/m <sup>2</sup>
Cu(111)	4.5 J/m <sup>2</sup>	<b>2.0 J/m<sup>2</sup></b>

- Calculate interfacial energies
- Need several simulations
  - Cu(100), Ag(100), Cu(111), Ag(111)
  - All separately, and all combinations
- Model gets surface energies correct (within 20%)
- Indicates strong preference for Cu{111}/Ag{111}



# Conclusions

- Nanoparticles will bond
  - Bulk phase diagram indicates differently
  - Low temperature bonding is possible
- Preference is for Ag{111} on Cu{111}
  - Predicted by models
  - Verified by experiments
- Interfacial energy is likely explanation